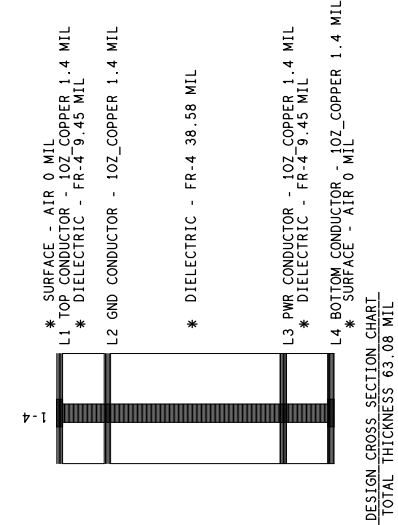
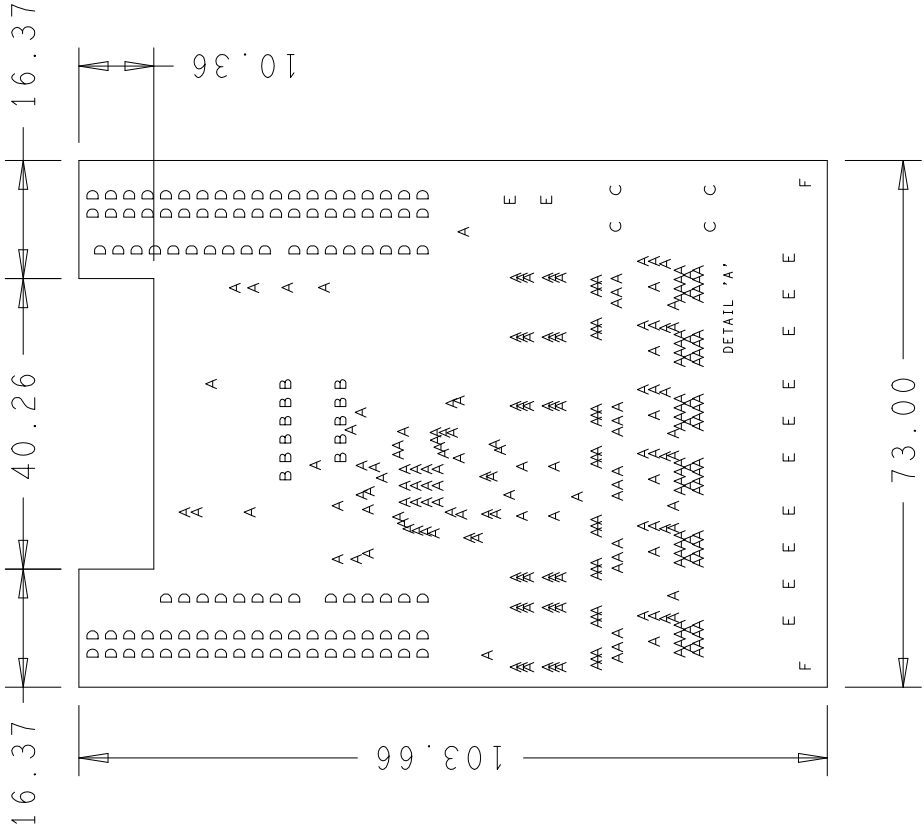




Finished Hole Tolerance - All units are in Inches -			
Finish Hole Diameter	Plated Through Finish Hole Diameter		Non Plated Through Finish Hole Diameter
	+0.002/-FHS*		
0.008"-0.013"	+/-0.003"		+/-0.002"
0.014"-0.063"	+/-0.003"		+/-0.002"
0.064"-0.156"	+/-0.004"		+/-0.003"
0.157"-0.250"	+/-0.007"		+/-0.004"
0.251" and up	+/-0.007"		+/-0.005"
0.125"	Non Plated Only		+0.003/-0.000"

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED_SIZE	PLATED	QTY
A	12.0	PLATED	236
B	35.0	PLATED	11
C	40.0	PLATED	4
D	44.0	PLATED	108
E	55.0	PLATED	12
F	125.98	NON-PLATED	2

TOTAL HOLES: 373

UNIT : mm
(mils).

REVISION DATE		Description		Symbol	
APMS Group		AGRATE B. ITALY		STDRIIVE181	
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TOLERANCE UNLESS NOTED		ISO		SCALE: 1 : 1	
UNIT=MM		ANG.		REV. 1.0	
linear		0 >10 <10		Material	
midle		>50 <200		Treatment and surface finishing	
accurate		>200 <200		±1°	
Drawn		RIGO M.		date	
Approved		25-May-2026		date	

FABRICATION NOTE :

- 1:FABRICATE USING LATEST REVISION OF IPC-6012B CLASS 2 OR ABOVE
- 2:FABRICATE USING MASTER ARTWORK EVLDRIVE181 RI FOR CIRCUIT PATTERN
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED STM REPRESENTATIVE
- 3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4:MATERIAL: FR4 RoHS COMPLIANT MINIMUM 170 C
SEE "DETAIL 'A'" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 5:SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE PER IPC-SM-840 (LATEST LEVEL), CLASS H. COLOR: BLUE
- 6:FINISH: ENIG Au>0.05u 3u<Ni<5u
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10:DESIGNATED AREA OR INSPECTION AND TEST STAMP
(MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 11:ON PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE
- 12:VENDOR TO PROVIDE BOARD STACK-UP AND IMPEDANCE (IF REQUIRED) APPROVAL PRIOR TO BOARD FABBRICATION STACK UP AND IMPEDANCE (IF REQUIRED) TO INCLUDE COPPER PLATING ON OUTER LAYERS.FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
VENDOR TO PROVIDE BOARD FOR IMPEDANCE TEST RESULTS AND COUPON (IF REQUIRED)
- 13:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION
TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 14:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 15:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND SHORTS. APPLY TEST STAMP IN REFERENCED AREA
- 16:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796